



DSN2, 1.0x0.6, 0.575P, (0402) CASE 152AC ISSUE D

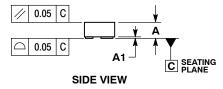
**DATE 27 APR 2017** 

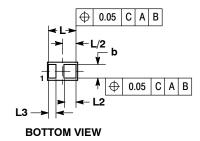


- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.

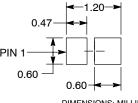
	MILLIMETERS		
DIM	MIN	MAX	
Α	0.25	0.31	
A1		0.05	
b	0.45	0.55	
D	1.00 BSC		
Е	0.60 BSC		
Ĺ	0.85	0.95	
L2	0.35	0.45	
12	0.20	0.30	

# 0.05 Ε 0.05 C **TOP VIEW**





## RECOMMENDED **SOLDER FOOTPRINT\***



**DIMENSIONS: MILLIMETERS** 

See Application Note AND8464/D for more mounting details

### **GENERIC MARKING DIAGRAM1\***

### **GENERIC MARKING DIAGRAM2\***





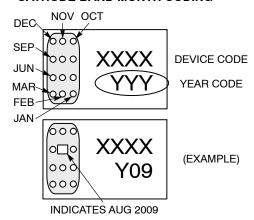
XXXX = Specific Device Code YYY = Year Code

XX = Specific Device Code

M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G", may or not be present. Some products may not follow the Generic Marking.

#### **CATHODE BAND MONTH CODING**



DOCUMENT NUMBER:	98AON40464E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	DSN2, 1.0X0.6, 0.575P, (0402)		PAGE 1 OF 1

onsemi and Onsemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries, onsemi reserves brisefin and of 160 m are trademarked so defined values of services and of the confined values and of the values of the confined values and of the values of the confined values and of the values of the v special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.